

## VG SERIES VG-502MKI8

### ■ SPECIFICATION

Wafer Size		3" to 8" PAT.1868779
Grinding Method		Continuous down feed
Grinding Spindles	Number of spindles Spindle speed Type of spindle bearing Spindle motor Spindle grinding feed speed Spindle up/down feed motor	2 Axis Max. 3600rpm Air bearing 2.2kW 4P built-in type, inverter drive 1 to 999 $\mu$ /min 200W AC Servo motor
Index Table	Number of vacuum chuck Speed of vacuum chuck Vacuum chuck driving motor Index motor	4 rotary chuck table 1 to 999rpm 1.1kW AC Servo motor 0.4kW
Automatic Sizing Device	Wafer thickness measuring system Wafer minimum setting size	2 point system in-process gauge 1 $\mu$ m
Table Cleaning Device	Table cleaning system	Wafer + Brush cleaning(Ceramic block)
Wafer cleaning Device	Wafer cleaning system	Wafer + Brush and Spinner
Automatic Loading and Unloading Device	Number of cassettes Wafer size Wafer address	Horizontally 2 cassettes Max. 8" inches Provided
Vacuum Pump Unit (option)	Vacuum pump Pressure Exhaust Water supply	1.5kW 40 Torr 40m <sup>3</sup> /hr. 5 liter/min (city water)
Utilities	Electricity supply Grounding resistance Noise Wattage Water supply for grinding Water supply for cleaning Air supply	3 phase AC200V 50A Less 100 $\Omega$ Less 1000V of 500ns pulse 17 kVA 12 to 15 liter/min (8"= 20 liter/min) 8 liter/min (any temperature) 60 liter/min 5.5 kgf/cm <sup>2</sup> G
Machine size		2700W/1550D/1770H
Weight		3900kg to 4600kg
Through put	depending on setting	6" = 80pcs/hr., 8" = 70pcs/hr.
Grinding Accuracy	Thickness in a wafer Thickness among wafers Roughness	6" = 1.0 $\mu$ m or less, 8" = 1.5 $\mu$ m or less 6" = 1.5 $\mu$ m or less, 8" = 2.0 $\mu$ m or less 6" = 0.1 $\mu$ m Rmax. or less, 8" = 0.2 $\mu$ m Rmax. or less